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FIG. 1

(UNIT:mm)

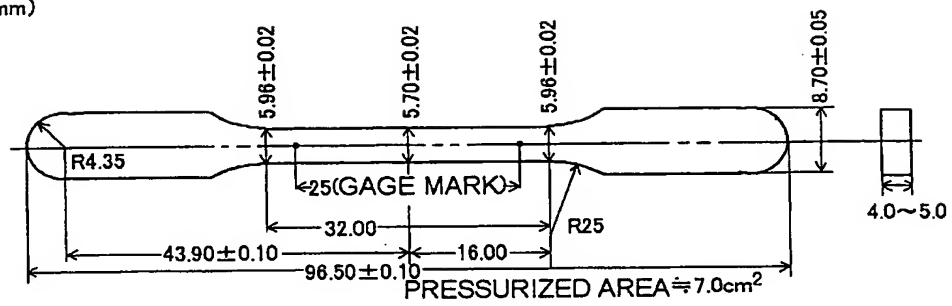


FIG. 2  
THE TENSILE STRENGTH OF CuNiSi AND  
CuSnNiSi SINTERED MATERIALS ( $\sigma_b$ )

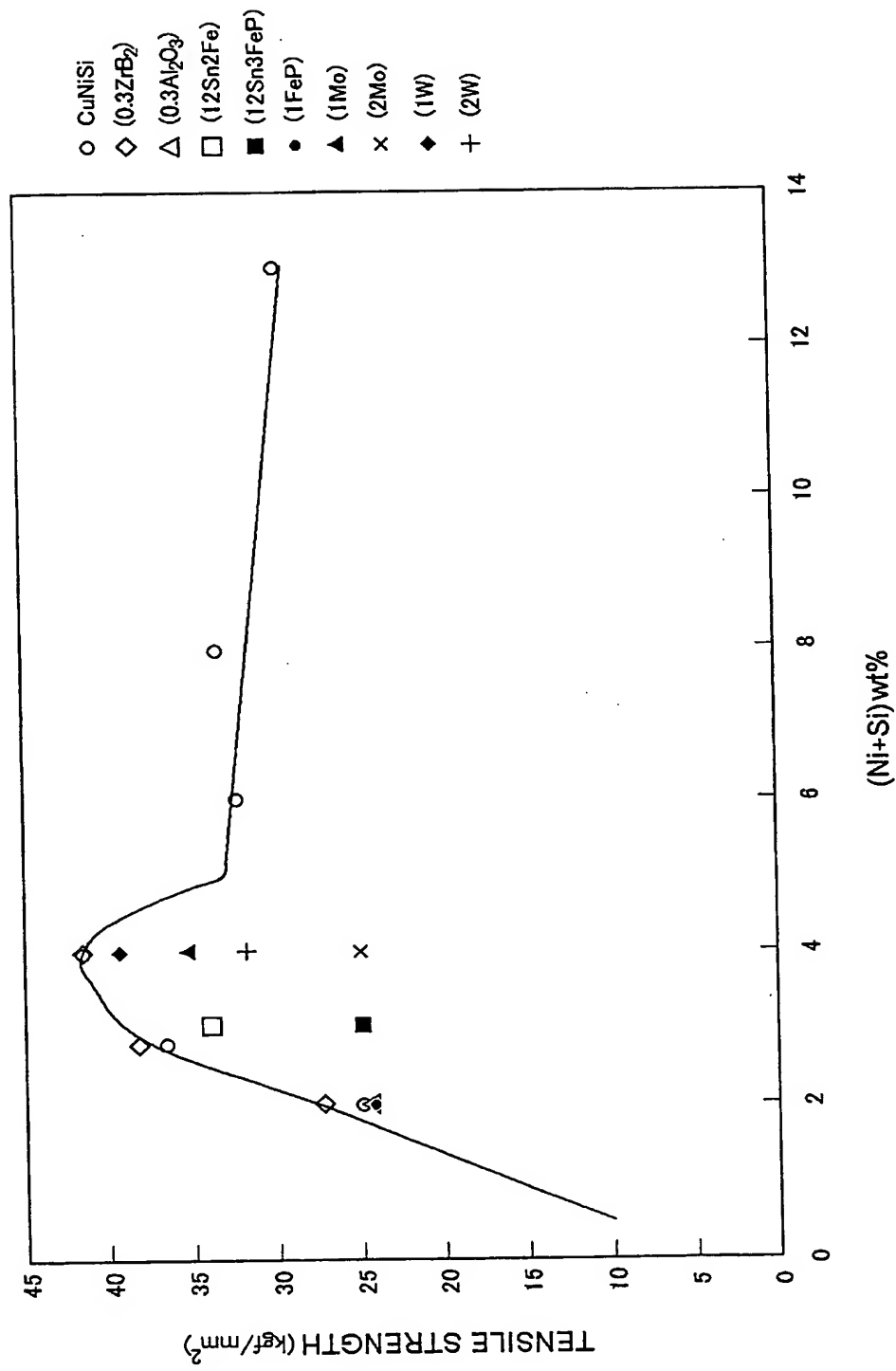
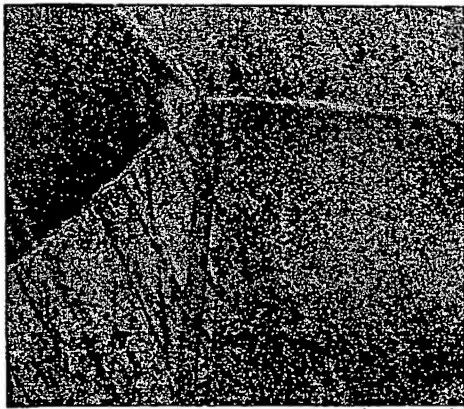


FIG. 3

THE STRUCTURES OF Cu-Ni-Si BASED SINTERED COMPACTS  
(A MAGNIFICATION OF  $\times 400$ )  
(SINTERING CONDITION  $1100^{\circ}\text{C} \times 1\text{HR}$ )

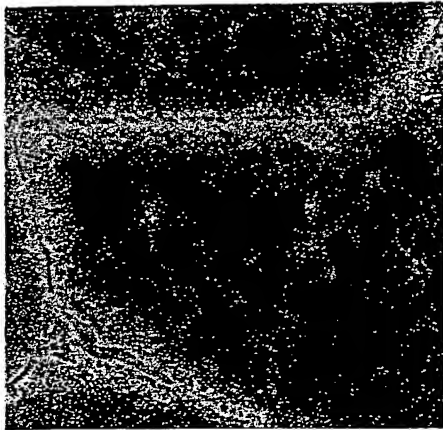


a) Cu-3Ni-1Si

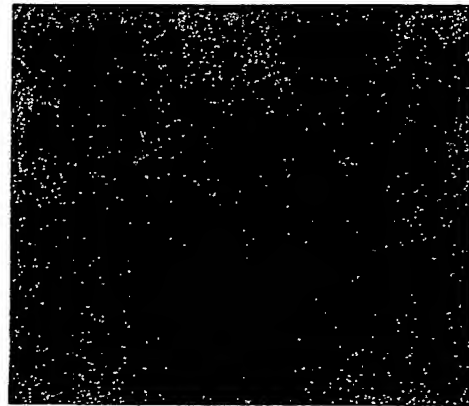
25  $\mu\text{m}$



b) Cu-4.5Ni-1.5Si



c) Cu-6Ni-2Si



d) Cu-10Ni-3.33Si

FIG. 4

THE STRUCTURE OF A Cu-3Ni-1Si-0.5SiO<sub>2</sub> BASED  
SINTERED COMPACT  
(A MAGNIFICATION OF  $\times 100$ )  
(1100°C  $\times$  1HR)

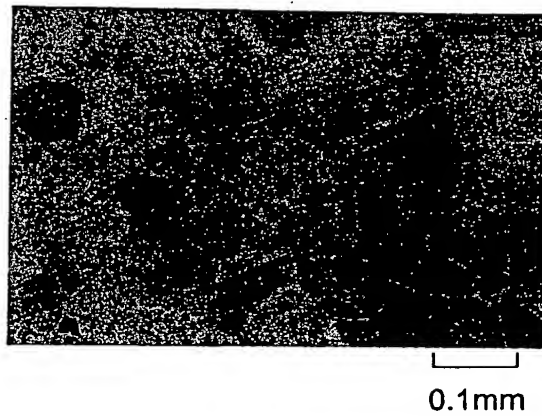


FIG. 5

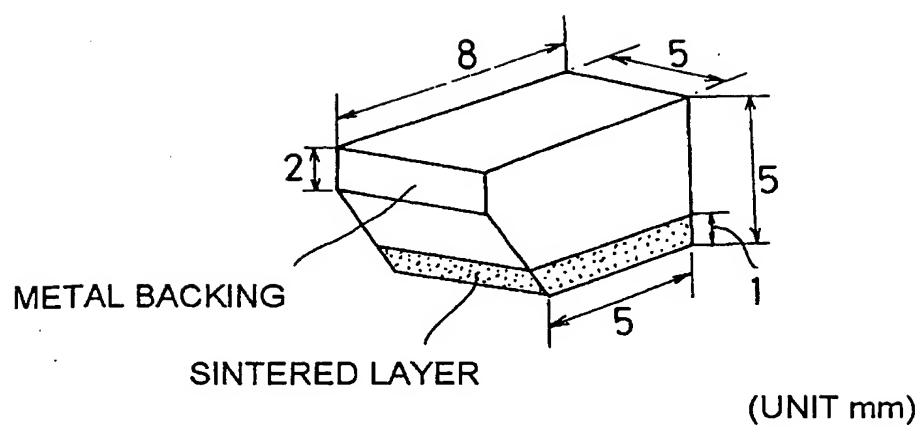
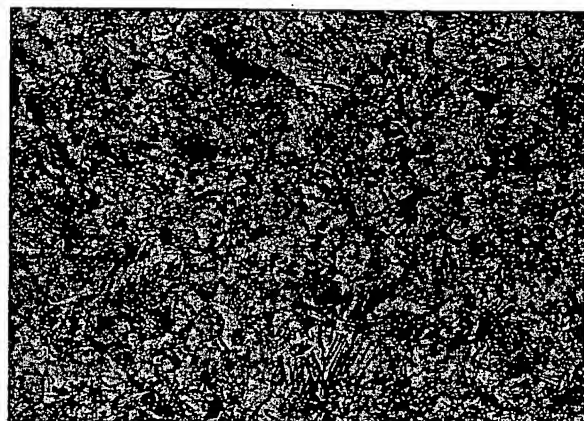


FIG. 6

THE STRUCTURE OF A Cu-10Sn-10Ni-0.55FeP-3Pb (B16)  
BASED SINTERED COMPACT  
(850°C × 1HR)



25  $\mu$  m

FIG. 7

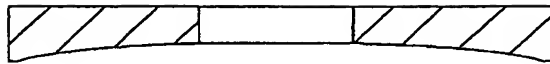




FIG. 8

